TPS3423, TPS3424

TPS3423、TPS3424、Nano-Power プッシュボタン コントローラ、バッテリ フ レッシュネス シールのための遅延設定が可能

1 特長

- 動作電圧範囲:1V~6V
- ナノアンペア単位の電源電流:18nA (標準値)
- プッシュボタン ピンの HBM ESD 定格:±8kV
- プログラム可能な短押しおよび長押し時間
 - TPS3423、TPS3424 固定タイミング オプション:
 - 短押し時間:50msec~13sec
 - 長押し時間:1sec~30sec
 - タイマ精度 (最大値):±10%
 - TPS3424:外付けコンデンサを使ってユーザーに よるプログラムが可能 (50msec~50sec)
- 出力構成:
 - リセット構成:
 - プッシュプル/オープンドレイン、アクティブ High / Low
 - ラッチあり/ラッチなし
 - ラッチなしバージョンでは、100msec~1secの パルス オプション
 - INT 設定:
 - オープンドレイン、アクティブ Low
 - ラッチなし (100msec~1sec のパルス幅)
- KILL 機能:ホストがリセット出力を制御可能
- ピン互換の8ピンおよび6ピンのDRLパッケージで 供給

2 アプリケーション

- ウェアラブル
- ゲーム機
- ホーム シアター エンターテインメント
- プリンタ
- ヘルスケア
- ポータブル エレクトロニクス
- ファクトリ オートメーション / 制御

3 概要

TPS3423 および TPS3424 はプッシュボタン コントローラ であり、短押しと長押しをさまざまな条件で独立して検出で きます。これらのデバイスは、プッシュボタンごとに最大 2 つの出力 (RESET $\ge \overline{\text{INT}}$) を備えており、電圧レギュレー タやサーキットブレーカのイネーブル、指定された押下期 間に対するワンショットの生成、マイクロコントローラへの割 り込みの送信など、さまざまな使用事例に使用できます。 このデバイスは、短押しと長押しの両方に対して割り込み パルスを生成し、マイクロコントローラに通知します。 RESET 出力は、デバイス構成に基づいて状態が変化し ます。

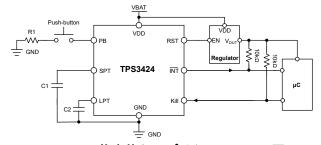
18nA の非常に低い消費電力により、バッテリ駆動デバイ スの製品保管期間の延長に貢献します。このデバイスは、 必要なボタンの押下が検出されるまで、電源ツリーが無効 の状態を維持します。この機能は、バッテリーフレッシュネ スシールと呼ばれています。

TPS3423/4 は、短押しおよび長押しの時間について固定 タイミングオプションで供給されます。設計者にフレキシビ リティを提供するため、TPS3424 は、外付けコンデンサに より短押しおよび長押しの時間をユーザーがプログラムす ることも可能です。TPS3424 の KILL ピンを使用すると、 マイクロコントローラからのフィードバックによる RESET の デアサートが可能になります。

製品情報

2422.00.00						
部品番号	パッケージ ⁽¹⁾	パッケージ サイズ ⁽³⁾				
TPS3423	DRL (SOT-5X3)	2.10mm × 1.60mm				
1733423	DRL (SOT-5X3) (2)	1.60mm × 1.20mm				
TPS3424	DRL (SOT-5X3)	2.10mm × 1.60mm				
	DRL (SOT-5X3) (2)	1.60mm × 1.20mm				

- 利用可能なすべてのパッケージについては、データシートの末尾 にある注文情報を参照してください。
- プレビュー版パッケージ
- パッケージ サイズ (長さ×幅) は公称値であり、該当する場合はピ ンも含まれます



TPS3424 代表的なアプリケーションの図



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4 Device Comparison

図 4-1 and 図 4-3 shows the device nomenclature of the TPS3423 and TPS3424, for output / push-button input, short press and long press, interrupt, reset and kill timing options. 図 4-2 extends nomenclature of TPS3423 to provide 2 different timing option for channels. Refer セクション 7 for more details. Contact TI sales representatives or on TI's E2E forum for detail and availability of other options.

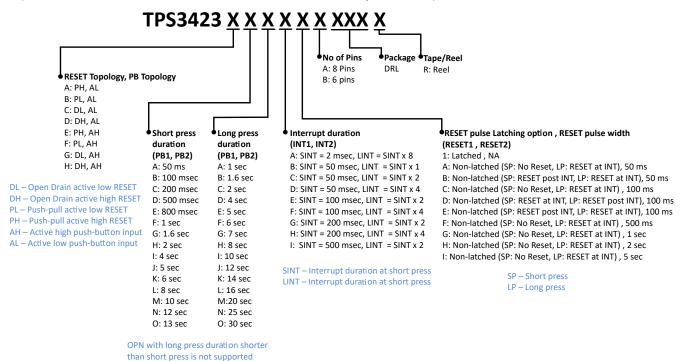


図 4-1. Dual Push-Button Nomenclature

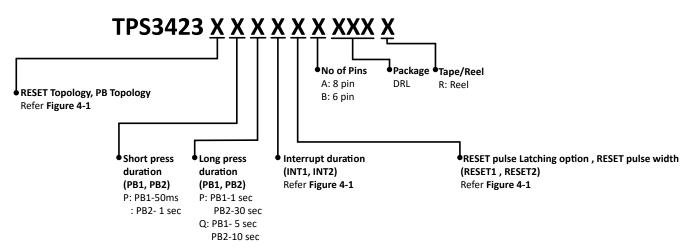


図 4-2. Dual Push-Button Extended Nomenclature



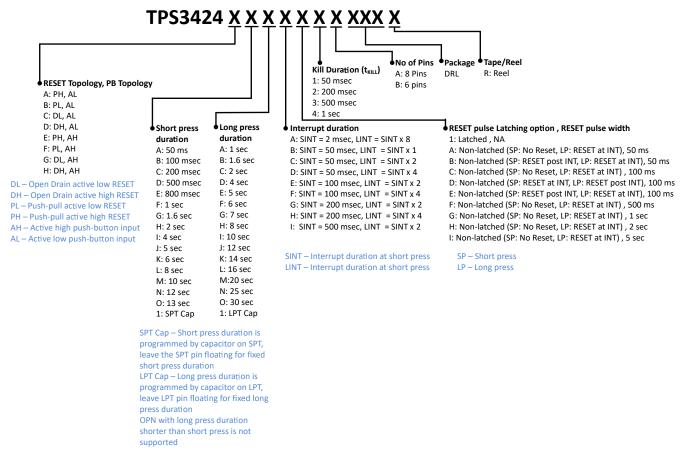


図 4-3. Single Push-Button Nomenclature

TPS3423/4 belongs to family of devices offering different feature sets as highlighted in Device Information.

Device Information

PART NUMBER	NO. OF PUSH-BUTTONS	PUSH-BUTTON TIMING OPTION	KILL FEATURE
TPS3423	2	Fixed	No
TPS3424	1	Fixed , programmable with external capacitor	Yes

資料に関するフィードバック(ご意見やお問い合わせ) を送信

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English Data Sheet: SNVSCN9



5 Pin Configuration and Functions

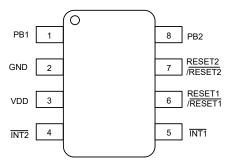


図 5-1. Pin Configuration Option: TPS3423
DRL Package
8-Pin SOT-5X3
Top View

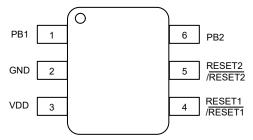


図 5-2. Pin Configuration Option TPS3423

DRL Package
6-Pin SOT-5X3

Top View

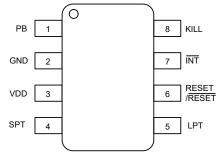


図 5-3. Pin Configuration Option TPS3424

DRL Package
8-Pin SOT-5X3

Top View

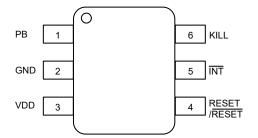


図 5-4. Pin Configuration Option TPS3424

DRL Package
6-Pin SOT-5X3

Top View



表 5-1. TPS3423 - Pin Functions

	TPS3423				
PIN NAME	8 PIN SOT-5X3	6 PIN SOT-5X3	I/O	DESCRIPTION	
PB1	1	1	1	Push-button input 1, refer セクション 7.3.1.1 for additional details.	
GND	2	2	-	Ground connection for IC.	
V _{DD}	3	3	I	Supply connection, connect a 0.1µF capacitor near the pin for best performance.	
INT2	4		0	Interrupt output for push-button input 2, INT2 is open drain active low output which toggles from every short press and long press on push-button input 2 as described in セクション 7.3.2.1	
INT1	5		0	Interrupt output for push-button input 1, INT1 is open drain active low output which toggles from every short press and long press on push-button input 1 as described in セクション 7.3.2.1	
RESET1/ RESET1	6	4	0	RESET output for push-button input 1. The response of RESET to short press and long press is described in セクション 7.3.2.2.	
RESET2/ RESET2	7	5	0	RESET output for push-button input 2. The response of RESET to short press and long press is described in セクション 7.3.2.2.	
PB2	8	6	I	Push-button input 2, refer セクション 7.3.1.1 for additional details.	



表 5-2. TPS3424 - Pin Functions

TPS3424				
PIN NAME	8 PIN SOT-5X3	6 PIN SOT-5X3	I/O	DESCRIPTION
РВ	1	1	ı	Push-button input, refer セクション 7.3.1.1 for additional details.
GND	2	2	-	Ground connection for IC.
V _{DD}	3	3	I	Supply connection, connect a 0.1µF capacitor near the pin for best performance.
SPT	4			Connect capacitor to program short press time as described in セクション 7.3.1.1 for SPT Cap version.
LPT	5		0	Connect capacitor to program long press time as described in セクション 7.3.1.1 for LPT Cap version.
RESET/ RESET	6	4	0	RESET output for the device. The response of RESET to short press and long press is described in セクション 7.3.2.2.
INT	7	5	0	Interrupt output. INT is open drain active low output which toggles from every short press and long press on push-button input as described in セクション 7.3.2.1
KILL	8	6	I	Kill is feedback from the host. RESET can be de-asserted in the latched version by pulling KILL low. Connect this pin to V _{DD} if not used. Please refer セクション 7.3.1.3 for additional details.



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

1 3 1		MIN	MAX	UNIT
				V./
	V_{DD}	-0.3	6.5	V
Voltage	V _{PB} ⁽¹⁾	-0.3	V _{DD} + 0.3	V
	V _{KILL} ⁽¹⁾	-0.3	V _{DD} + 0.3	V
Current	I _{RESET/RESET}	-6	6	mA
Temperature ⁽²⁾	Operating free-air temperature, T _A	-40	125	°C
Storage temperature range	T _{stg}	-65	150	°C

⁽¹⁾ Stresses beyond values listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD) Ele		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (PB pin only)	±8000	
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101	±750	

(1) HBM for all the pins except PB

6.3 Recommended Operating Conditions

		MIN	NOM MAX	UNIT
V_{DD}	Supply pin voltage	1	6	V
V _{PB}	Push-button pin input voltage	0	V_{DD}	V
V _{KILL}	KILL pin Voltage	0	V_{DD}	V
V _{INT}	Interrupt pin voltage	0	V_{DD}	V
V _{RESET/RESET}	Output pin voltage	0	V_{DD}	V
I _{RESET/RESET}	Output pin current	0	5	mA
T _A	Ambient temperature	-40	125	°C
C _{SPT}	SPT capacitor ⁽¹⁾		125	nF
C _{LPT}	LPT capacitor		125	nF

(1) SPT capacitor value must be lower than LPT capacitor value



6.4 Thermal Information

		TPS3423 / TPS3424	
	THERMAL METRIC ⁽¹⁾	DRL (SOT-583)	UNIT
		8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	122.8	°C/W
R _{0JC(top)}	Junction-to-case (top) thermal resistance	68.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	31.1	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	2.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	30.5	°C/W
R _{0JC(bot)}	Junction-to-case (bottom) thermal resistance	NA	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics

At 1V <V $_{DD}$ <6V, SPT = LPT = Open, KILL = VDD, C $_{RESET}$ = 50pF, \overline{INT} = 10K Ω pull up to V $_{DD}$ and over the operating free-air temperature range of - 40°C to 125°C, unless otherwise noted. Typical values are at T $_A$ = 25°C.

	PARAMETER	TEST	CONDITION	MIN	TYP	MAX	UNIT
POWER SUP	PPLY					-	
V_{DD}	Supply Voltage			1		6	V
		\/ - 2\/	T _A = 25°C		18	24	
ı	Standby supply	V _{DD} = 3V	$T_A = -40$ °C to 85°C			90	nA
I _{DD} (Standby)	current ⁽¹⁾	V _{DD} = 6V	$T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$		23	100	IIA
		V _{DD} = 6V				350	
Push-button	PIN						
	Supply current when V $_{PB}$ = 0V (two push- button is pressed) ⁽²⁾					12	
I _{DD(Active)}	Supply current when V PB = 0V (one push- button is pressed) ⁽²⁾	V _{DD} = 3V				7	μΑ
	Supply current when $V_{PB} = VDD$ (both-push buttons are pressed) ⁽³⁾					1.5	
V _{IH(PB / PB)}	PB Logic high input ⁽²⁾	V _{DD} = 3V		0.8*V _{DD}			
V _{IL(PB / PB)}	PB Logic low Input ⁽²⁾	V _{DD} - 3V			0.3	*VDD	
R _{PB}	PB pin internal pull-up / pull-down resistance ⁽²⁾				1000		kΩ
INT and RES	ET			1			
V	Low level output voltage	$V_{DD} = 1V$, $\overline{INT} = 100\mu A$ $V_{DD} = 3V$, $\overline{INT} = 1mA$				200	mV
V _{OL(INT)}	Low level output voltage					300	IIIV
I _{LKG(ĪNT)}	Open drain output leakage current for INT	V _{DD} = V _{Pullup} = 6V				70	nA



6.5 Electrical Characteristics (続き)

At 1V <V $_{DD}$ <6V, SPT = LPT = Open, KILL = VDD, C $_{RESET}$ = 50pF, \overline{INT} = 10K Ω pull up to V $_{DD}$ and over the operating free-air temperature range of - 40°C to 125°C, unless otherwise noted. Typical values are at T $_A$ = 25°C.

PA	RAMETER	TEST CONDITION	MIN	TYP MAX	UNIT	
	Low level output voltage (Open Drain)	$V_{DD} = 1V$, $I_{(RESET/RESET)} = 300\mu A$		200		
V _{OL(RESET/}	Low level output voltage (Push-Pull) ⁽⁴⁾	$V_{DD} = 1V$, $I_{(RESET/RESET)} = 300\mu A$		200	mV	
RESET)	Low level output voltage (Open Drain)	V _{DD} = 3V, I _(RESET/RESET) = 5mA		300		
	Low level output voltage (Push-Pull) ⁽⁴⁾	V _{DD} = 3V, I _(RESET/RESET) = 5mA		300		
V _{OH(RESET/}	High level output voltage (Push-Pull) ⁽⁴⁾	$V_{DD} = 1V$, $I_{(RESET/RESET)} = 200\mu A$	0.7*V _{DD}			
RESET)	High level output voltage (Push-Pull) ⁽⁴⁾	V _{DD} = 3V, I _(RESET/RESET) = 5mA	0.7* _{VDD}			
I _{LKG (RESET/RESET)}	Open drain output leakage current for (RESET)	$V_{DD} = V_{Pullup} = 6V$, $R_{Pullup} = 10k\Omega$		70	nA	
KILL, SPT, LF	KILL, SPT, LPT					
I _{KILL}	Kill Input current			25	nA	
V _{KILL_L}	KILL logic low input			0.3*V _{DE}		
V _{KILL_H}	KILL logic high input		0.7*V _{DD}			

⁽¹⁾ PB pin is floating.

6.6 Timing Requirements

At 1V <V_{DD} <6V, SPT = LPT = Open, KILL = VDD, C_{RESET} = 50pF, \overline{INT} = 10K Ω pull up to V_{DD} and over the operating free-air temperature range of - 40°C to 125°C, unless otherwise noted. Typical values are at T_A = 25°C.

	Parameter	Test Condition	MIN	TYP	MAX	UNIT
	Short press duration accuracy for fixed version ⁽¹⁾		-10		10	%
t _{SP} Accuracy	Short press duration accuracy for adjutable version ⁽¹⁾	SPT = 330pF, LPT = 4.7nF	-20		20	%
	Long press duration accuracy for fixed version		-10		10	%
t _{LP} Accuracy	Long press duration accuracy for adjutable version	SPT = 330pF, LPT = 4.7nF	-20		-20	%
t _{SINT} Accuracy	Interrupt pulse width accuracy for PB long press		-10		10	%
t _{LINT} Accuracy	Interrupt pulse width accuracy for PB short press		-10		10	%
t _{KILL} Accuracy	PB/KILL debounce accuracy when RESET deaaserts in latched version		-10		10	%
t _{RESET}	Reset pulse duration (non latched) - Accuracy		-10		10	%
t _{GI(KILL)}	Glitch Immunity at KILL pin			250		ns
t _{PD(KILL)}	KILL falling edge to RESET assert delay			300		ns

(1) t_{SPD} should always be less than t_{LPD} .

⁽²⁾ PB pin as active low.

⁽³⁾ PB pin as active high.

⁽⁴⁾ This spec holds true both for active high RESET and active low RESET.



6.7 Timing Diagrams

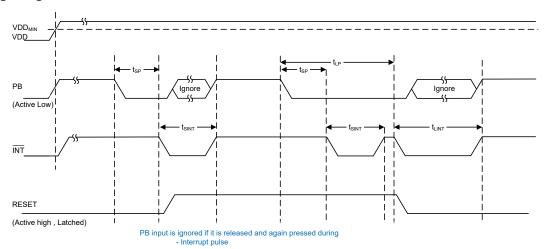


図 6-1. Timing Diagram: Latched RESET

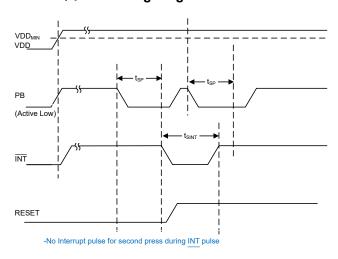


図 6-2. Timing Diagram: Example of PB Input Ignore

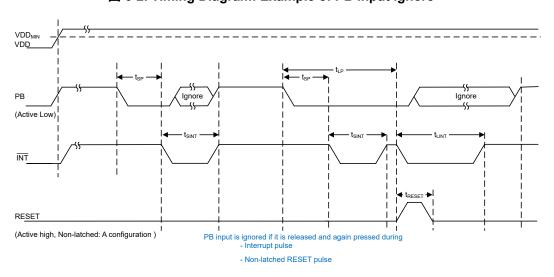


図 6-3. Timing Diagram: Non-Latched RESET

11



(SP: No Reset, LP: RESET at INT)

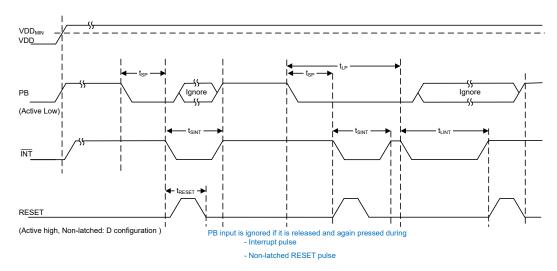
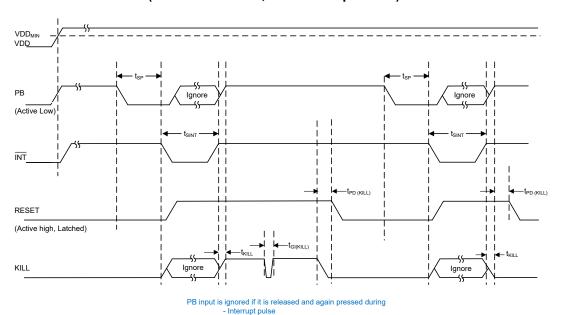


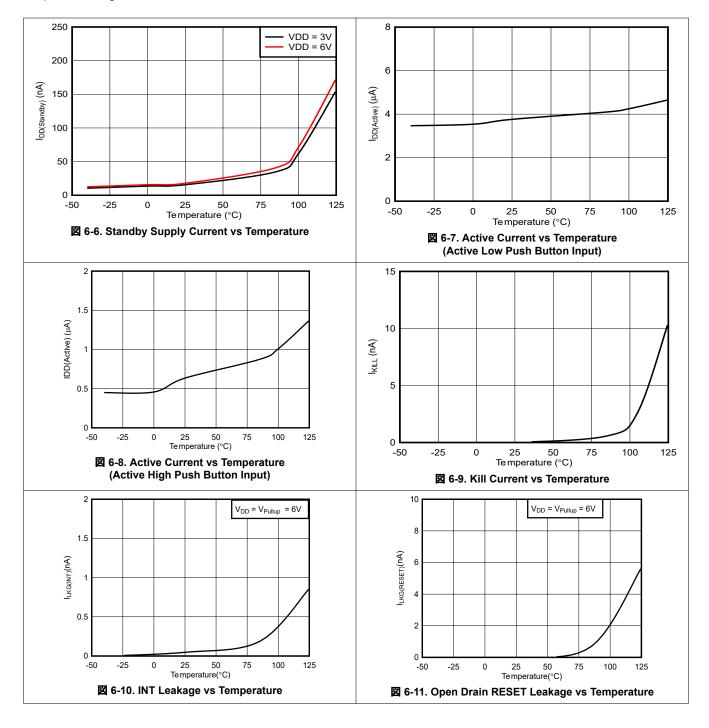
図 6-4. Timing Diagram: Non-Latched RESET (SP: RESET at INT, LP: RESET post INT)



- KILL debounce

6.8 Typical Characteristics

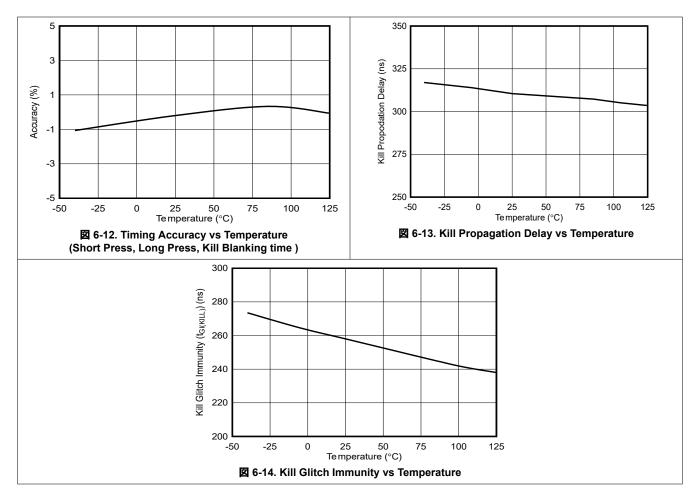
At V_{DD} = 6V, SPT = LPT = Open, KILL = VDD, C_{RESET} = 50pF, INT = 10K pull up to V_{DD} and over the operating free-air temperature range of - 40°C to 125°C, unless otherwise noted.





6.8 Typical Characteristics (continued)

At V_{DD} = 6V, SPT = LPT = Open, KILL = VDD, C_{RESET} = 50pF, INT = 10K pull up to V_{DD} and over the operating free-air temperature range of - 40°C to 125°C, unless otherwise noted.

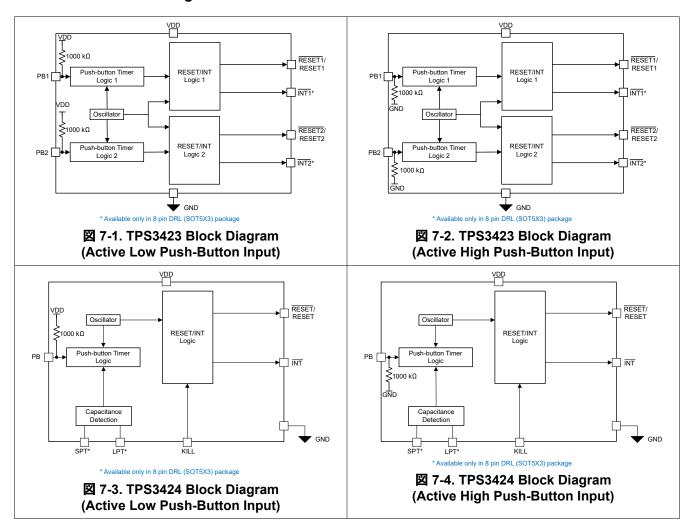


7 Detailed Description

7.1 Overview

The TPS3423 & TPS3424 are nano power push-button family which offer wide range of timing option for input (PB, KILL) and output (RESET, $\overline{\text{INT}}$) pins. This device family is available in two different pinout with 8 and 6 pin DRL package and various output and input configuration as per Device Comparison to support various applications. The pin placement enables use of either 6 pin or 8 pin device for a single 8 pin layout.

7.2 Functional Block Diagrams



7.3 Feature Description

7.3.1 Inputs

This section discusses the inputs of the TPS3423 & TPS3424 devices.

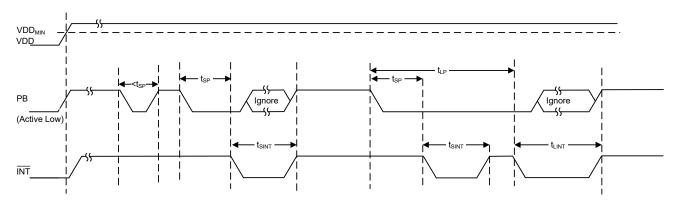
7.3.1.1 Push-Button Input (PB)

Push-button input (PB) for TPS3423 and TPS3424 is available in active low and active high configuration as per 表 7-1 as shown from $ext{ ext{ iny 7-4}}$.

表 7-1. Push-Button Configuration

PUSH-BUTTON CONFIGURATION	INTERNAL RESISTOR ORIENTATION	PB TRIGGER STATE			
Active low	1000k Ω , pulled up to VDD	Falling edge on PB pin if INT is not asserted.			
Active High	1000k Ω , pulled down to GND	Rising edge on PB pin if INT is not asserted.			

PB pin should be connected to a switch with ON resistance less than 20% of the pull-up / pull-down resistance to provide the correct PB input trigger for the device.



PB input is ignored if it's width is less than t_{sp}.

PB input is ignored if it is released and again pressed during interrupt pulse.

図 7-5. Push Button Functionality



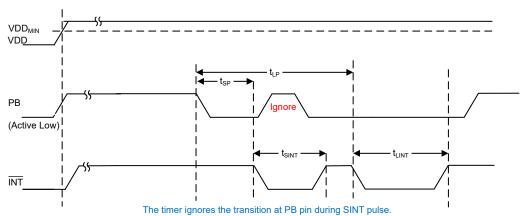


図 7-6. Push Button Transition Behavior at INT Pulse

TPS3423 has two independent push-button pins PB1 and PB2. These pins are factory programmed for short press (t_{SP}) and long press (t_{LP}) duration. TPS3424 has single PB pin. PB pin in TPS3424 is available both in fixed timing and user programmable option (8-pin DRL package) through capacitor connection on SPT and LPT pins. SPT and LPT pins must be floating for fixed timing option of TPS3424.

7.3.1.2 Push-Button Timing Programmability

TPS3424x11xxx8DRLR has options to program short press duration (t_{SP}) and long press duration (t_{LP}) with capacitor on SPT pin and LPT pin respectively. Equation 1 shows the relation between the press duration and the capacitance. If the pin is left floating, the device defaults to fixed timer of 50msec. Connecting a capacitor which provides less than 50msec press duration as per, programs to 50msec press duration. Make sure t_{LP} is greater than t_{SP} for proper device operation.

$$t_{SP} \text{ or } t_{LP}(\text{sec}) = 0.422 \times C(\text{nF}) \tag{1}$$

where

- Press duration is t_{SP} for SPT capacitor and t_{LP} for LPT capacitor.
- C is the value capacitance connected on SPT or LPT pin.

The device samples the value of capacitor at SPT and LPT at the time of power-up and stores that value. Changing the capacitor after power-up does not change the value of short press (t_{SP}) and long press (t_{LP})

7.3.1.3 KILL

KILL pin is used as a control input from the host for the latched RESET version of push-button device. A short press on PB pin asserts the RESET output of push-button in latched version. The host pulls KILL high once all the expected action from short press is completed like power tree start-up. The device ignores the KILL input for $t_{SINT} + t_{KILL}$ after short press time (t_{SP}), this allows sufficient time for host to monitor the expected tasks for short press.

The host doesn't pull KILL high if short press doesn't perform all expected actions and the push-button device de-asserts RESET output when KILL is low after the debounce time as shown in 🗵 6-5. Host can pull KILL low at any time to de-assert RESET without any long press on PB pin. KILL input is ignored for non-latched RESET configuration. Connect KILL pin to VDD if KILL feature is not used.

7.3.2 Outputs

This section discusses the outputs of the TPS3423/4 devices.

7.3.2.1 Interrupt (INT)

7.3.2.2 RESET / RESET

RESET output of the device supports multiple configurations as described in 表 7-2. This device is available in all combination as described in セクション 4.

表 7-2. Reset Configurations

PARAMETER	VALUE		
Latching option	Latched, Non-latched		
Logic	Active High (AH), Active Low (AL)		
Output configuration	Open Drain (OD), Push-Pull (PP)		

7.4 Device Functional Modes

Device Functional Modes summarizes the functional modes of the push-button device.

Device Functional Modes

VDD	PB (Active Low)	INT	RESET (Latched, Active high)	
VDD< 1V	Not Applicable	Undefined	Undefined	
1V ≤ VDD <6V	Low <t<sub>SP</t<sub>	No Pulse	No State change	
	Low >t _{SP}	Single pulse (SINT)	High	
	Low >t _{LP}	Two pulse (SINT, LINT)	Low	

8 Application and Implementation

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8.1 Application Information

Push-button controllers play an important role in any human-machine interface (HMI) design. They decode user inputs from single or multiple button presses, control system power or reset, and perform other essential user interface functions. TPS3423 and TPS3424 devices are designed to extend the shelf life of battery powered applications.

8.2 Typical Applications

8.2.1 Power Button Control with TPS3424

TPS3424 is designed for power button applications which need to put the system in deep sleep mode with very small standby power. TPS3424 controls enable for load switch or DC-DC converter in latched mode of RST pin.

An application diagram is shown in 🗵 8-1 with load switch TPS22919, where TPS3424 is used to control the power from HMI.

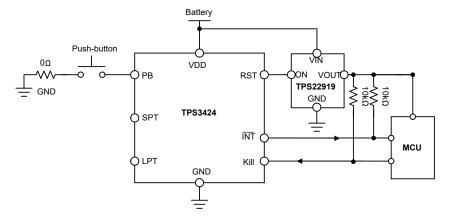


図 8-1. TPS3424 Application Diagram

8.2.1.1 Design Requirements

表 8-1 lists the design requirements for 図 8-1.

表 8-1. Design Requirements and Results

DESIGN REQUIREMENTS	DESIGN RESULT
HMI Button	PB
Supply = 3V	VDD = 3V
T _{ON} = 50ms	t _{SP} = 50ms
T _{OFF} = 2sec	t _{LP} = 2sec
MCU IO pin current rating < 500uA	ĪNT & KILL pull up = 10kΩ

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8.2.1.2 Detailed Design Procedure

8.2.1.2.1 PB and RESET Topology

Selection of push-button input topology depends on the HMI. The button press in this application shorts PB pin to GND with a low resistor, hence active low PB topology is chosen here. Selection of RESET pin topology depends on the ON pin behaviour of the load switch or the voltage regulator in power control applications. Active high latched REST is chosen topology is chosen here to turn-on the load switch at short press and turn-off at long press.

8.2.1.2.2 Short Press Time (t_{SP}) and Long Press Time (t_{LP}) selection

 t_{SP} = 50ms and t_{LP} = 2sec can be selected through the factory programmed option or placing capacitor at the SPT and LPT pin for programable option. Leave the SPT and LPT pin open as shown in \boxtimes 8-1 for factory programmed timing option. Equation 1 and Equation 2 shows the value for capacitor at SPT and LPT pin respectively for programming t_{SP} = 50ms and t_{LP} = 2sec in cap programable option.

$$C_{SPT}(nF) = 0pen$$
 (2)

$$C_{LPT}(nF) = \frac{2 \text{ sec}}{0.422} = 4.7$$
 (3)

8.2.1.2.3 Interrupt and Kill Feature

TPS3424 generated a pulse on $\overline{\text{INT}}$ pin for every valid short press and long press. This feature can be used as feature traverser (eg. showing different value on screen).

KILL feature enables host to control the RESET output of TPS3424 as described in $2992 \times 7.3.1.3$. KILL pin enables the host to put the system in deep sleep when unused for given time. Short KILL to V_{DD} pin if KILL feature is not used.

8.2.1.3 Application Curve

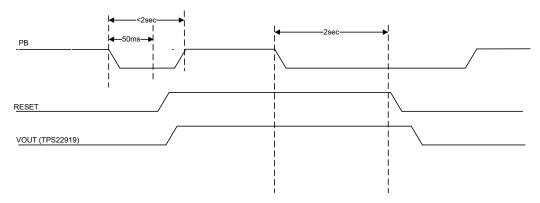


図 8-2. Power Control Through Load Switch

8.2.2 High Voltage Connection

Low current shunt regulator ATL431 enables the push-button to be used with 12V/24V battery powered application as shown in \boxtimes 8-3.



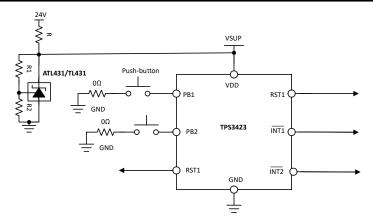


図 8-3. High voltage support with ATL431

8.3 Power Supply Recommendations

This device is designed to operate from an input supply with a voltage range between 1V and 6V. An input supply capacitor is not required for this device; however, if the input supply is noisy, then good analog practice is to place a 0.1µF capacitor between the VDD pin and the GND pin.

8.4 Layout

8.4.1 Layout Guidelines

Follow these guidelines for laying out the printed circuit board (PCB) that is used for the TPS3423 and TPS3424.

- Make sure that the connection to the VDD pin is low impedance. Good analog design practice recommends placing a 0.1µF ceramic capacitor as near as possible to the VDD pin.
- Place the external capacitor on close to LPT and SPT pin for TPS3424.
- Parasitic on LPT and SPT must be less than 50pF when these pins are floating for TPS3424.

8.4.2 Layout Example

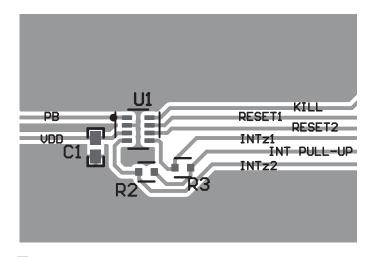


図 8-4. TPS3423: Layout Example (8-Pin DRL Package)



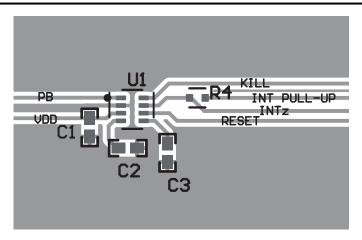


図 8-5. TPS3423: Layout Example (8-Pin DRL Package)

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9 Device and Documentation Support

9.1 ドキュメントの更新通知を受け取る方法

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9.5 用語集

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10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

С	hanges from Revision * (September 2024) to Revision A (December 2024)	Page
•	量産データのリリース	1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
PPS3423DAHGFADRLR	ACTIVE	SOT-5X3	DRL	8	4000	TBD	Call TI	Call TI	-40 to 125		Samples
PPS3424A11C13ADRLR	ACTIVE	SOT-5X3	DRL	8	4000	TBD	Call TI	Call TI	-40 to 125		Samples
TPS3423GAMDHADRLR	ACTIVE	SOT-5X3	DRL	8	4000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	D0001	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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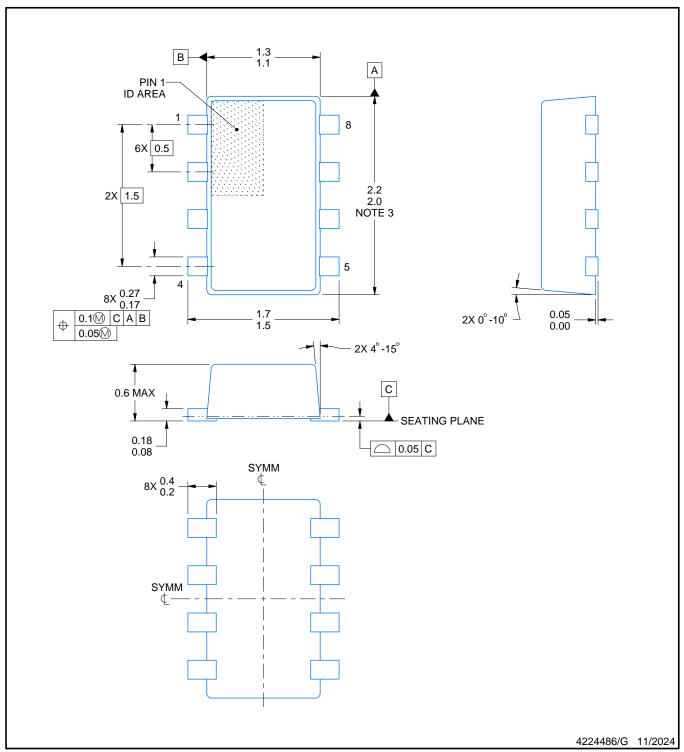
PACKAGE OPTION ADDENDUM

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PLASTIC SMALL OUTLINE

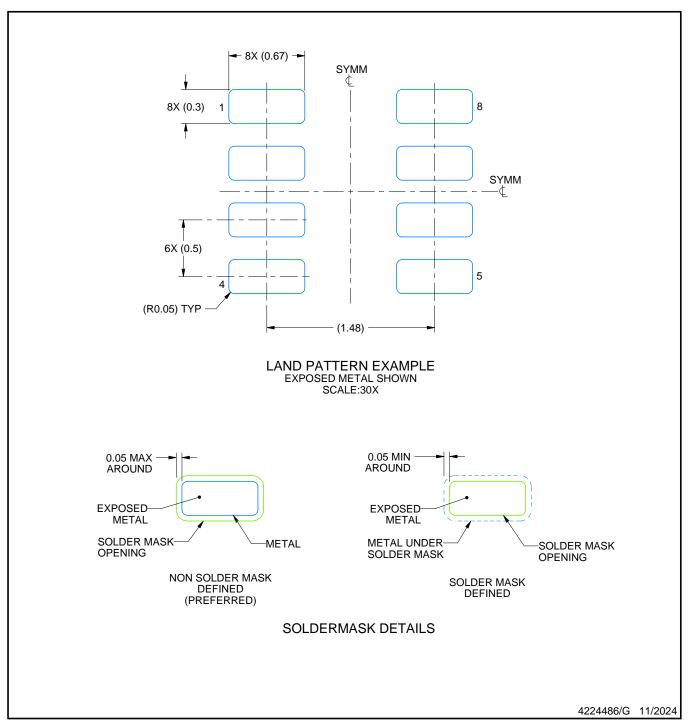


NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not accord 0.45 mercans side.
- exceed 0.15 mm per side.
- 4. Reference JEDEC Registration MO-293, Variation UDAD



PLASTIC SMALL OUTLINE

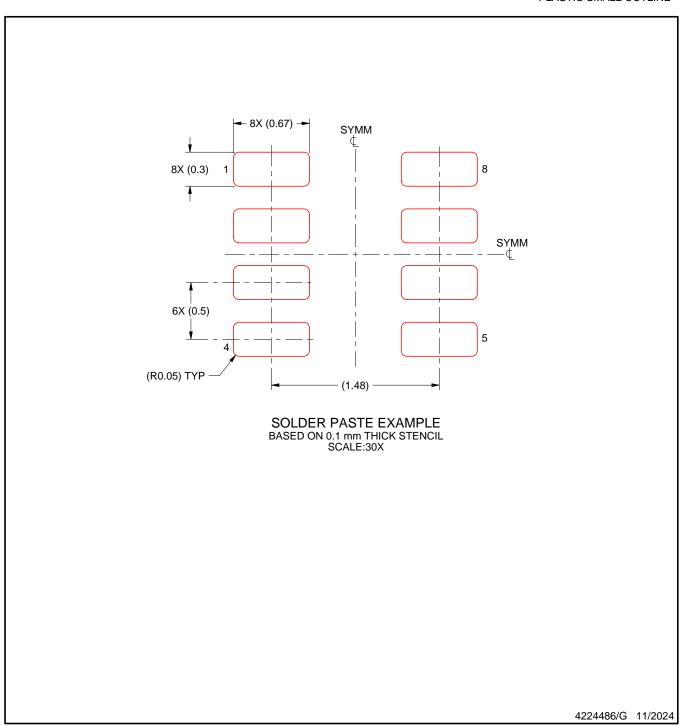


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.



PLASTIC SMALL OUTLINE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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